



## Material Content Data Sheet



<b>Sales Product Name</b>		BSF450NE7NH3		<b>Issued</b>		20. July 2018			
<b>MA#</b>		MA001030190							
<b>Package</b>		MG-WDSO-N-2-1		<b>Weight*</b>		49.87 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.774	3.56	3.56	35580	35580	
leadframe	non noble metal	copper	7440-50-8	45.429	91.11	91.11	911044	911044	
leadfinish	non noble metal	nickel	7440-02-0	0.121	0.24		2429		
	noble metal	silver	7440-22-4	0.482	0.97	1.21	9663	12092	
plating	non noble metal	nickel	7440-02-0	0.121	0.24	0.24	2429	2429	
glue	plastics	epoxy resin	-	0.107	0.21		2142		
	noble metal	silver	7440-22-4	0.656	1.32	1.53	13160	15302	
solder	non noble metal	copper	7440-50-8	0.005	0.01		107		
	noble metal	silver	7440-22-4	0.032	0.06		641		
	non noble metal	tin	7440-31-5	1.028	2.06	2.13	20606	21354	
passivation	plastics	epoxy resin	-	0.110	0.22	0.22	2199	2199	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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